June 15-17, 2026

Optical Interconnects and Packaging Conference

The Elizabeth Hotel
Fort Collins, CO

About Optical Interconnects and Packaging (OIP)

Optical interconnects and advanced packaging technologies are rapidly transforming the landscape of high-performance computing (HPC) and data communication. With applications spanning HPC, data centers, telecommunications, sensing, and aerospace, these technologies have drawn significant interest from both academia and industry. The development of next-generation optical interconnects requires a multidisciplinary approach, integrating innovations in materials, photonic device engineering, packaging solutions, and system-level design. As the demand for higher bandwidth, lower power consumption, and scalable architectures continues to grow, collaboration across disciplines becomes essential to unlock the full potential of optical interconnects and packaging solutions.

The Optical Interconnects and Packaging Conference (OIP) is a single track, collaborative event dedicated to solving the future of high-density optical interconnects and packaging including evolving applications in high-speed 200G/400G SerDes, energy efficient high density scale up/out interconnects, optical packaging and 3D-IC integration, next generation optical devices enabling high speed/low power, etc. Our mission is to advance all these fields through high-quality technical presentations as well as workshops, invited talks, and keynotes while fostering in-person interactions in an interdisciplinary setting. OIP gathers academic and industrial experts from multiple fields, including SerDes, optical devices/interconnects, AI, HPC, and packaging.

Call for Papers and Participation

OIP will be held as an in-person conference in Fort Collins, CO during June 15 – 17, 2026. Original, unpublished papers describing research and advancements in the following areas are solicited:

- Co-packaging & optical integration
- Light sources
- Advanced optical design solutions (inverse design, etc.)
- 2.5D and 3D integration
- High-volume manufacturing, assembly, and testing
- Packaging technologies (panel-/wafer-level packaging & integration, etc.)
- Materials for optical interconnects & packaging
- Photonic devices
- Advanced system architectures (chiplet-based systems, disaggregated systems, etc.)
- AI-driven optical interconnects
- Electronics for photonics (SerDes, TIAs, etc.)
- Emerging applications of photonics (quantum, AI, autonomous systems, etc.)

Call for Exhibits

If you are interested in exhibiting at OIP 2026, please contact Mahdi.Nikdast@colostate.edu.

Paper Submission

Authors are invited to submit full-length two-page, original, camera-ready and unpublished papers along with an abstract of at most 45 words. The two-page paper should include author names and information and be prepared based on the IEEE paper template. Charts, illustrations, figures, and references must fit within the two-page paper limit. The 45-word abstract will be used in the online program. The IEEE Xplore proceedings will only contain accepted papers that are presented at the conference.

Submission link: https://easychair.org/conferences/?conf=oip26

Important Dates

Paper submission deadline
March 16, 2026
Acceptance notification
May 4, 2026

Organizing Committee

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More Information

https://oip-conference.org/

Contact

Mahdi Nikdast, *Colorado State University*
Mahdi.Nikdast@colostate.edu